

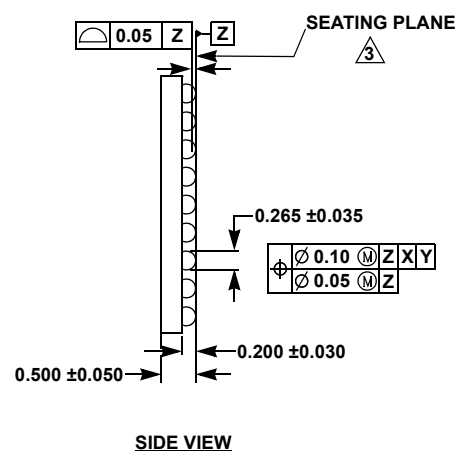
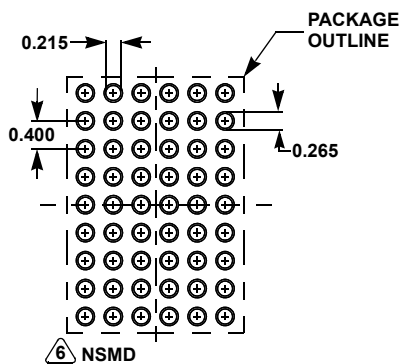
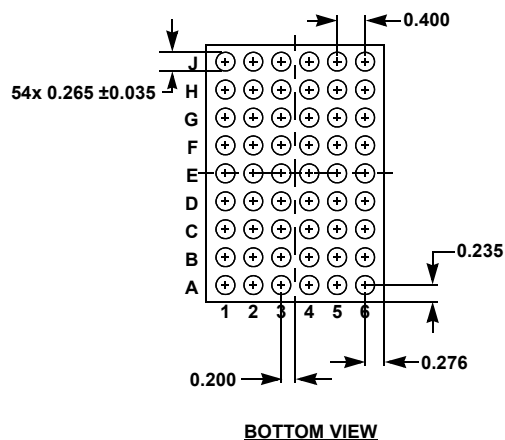
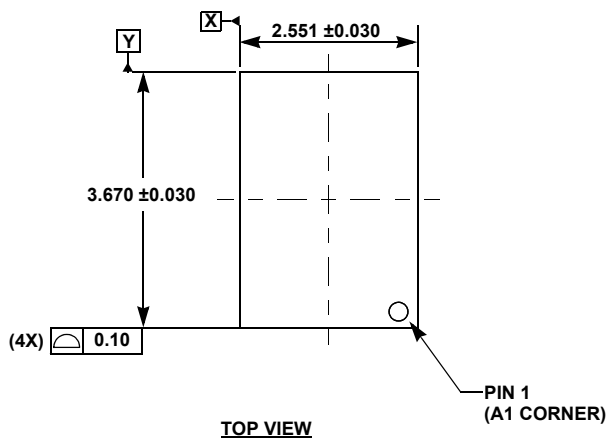
Plastic Packages for Integrated Circuits

Package Outline Drawing

W6x9.54

54 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm PITCH)

Rev 0, 10/15



NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASME Y 14.5M - 1994.
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z.
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).